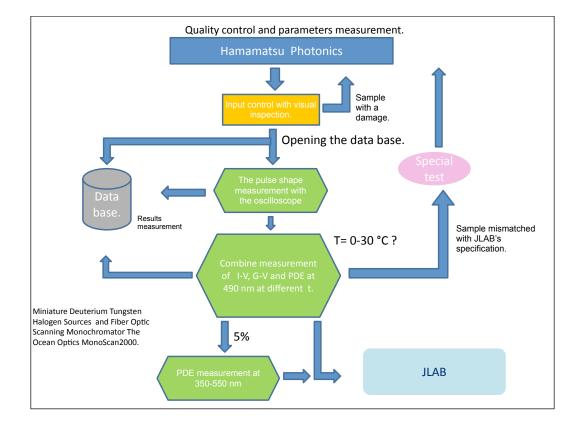
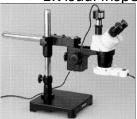
USM tests: the goals and methods of the tests, types and frequency of measurements.



1.Visual inspection of each SIPM cell of the array.



The test will be done with:

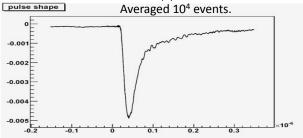
20X-40X-80X TRINOCULAR STEREO MICROSCOPE BOOM + CAMERA, X-Y GLIDING TABLE - MANUAL STAGE FOR MICROSCOPES, FIBER OPTIC Y-SHAPE DUAL LIGHT MICROSCOPE ILLUMINATOR

The pictures will be store at the data base.

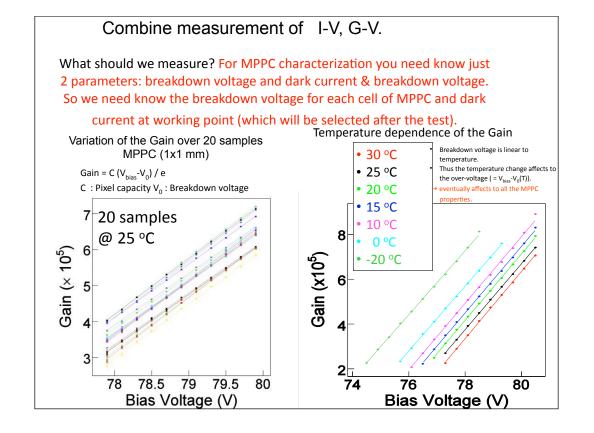
2. Pulse shape measurement with the digital oscilloscope (using a fast amplifier with low input impedance). The oscilloscope picture for each cell will be store at the data base. Fast LED (LED driver with a transistor in the avalanche mode) or laser (?). The light pulse should

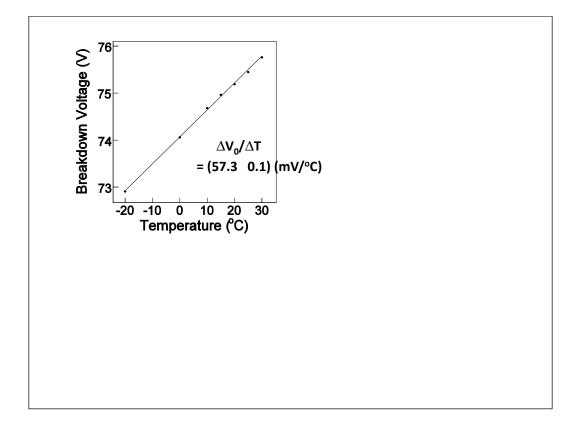


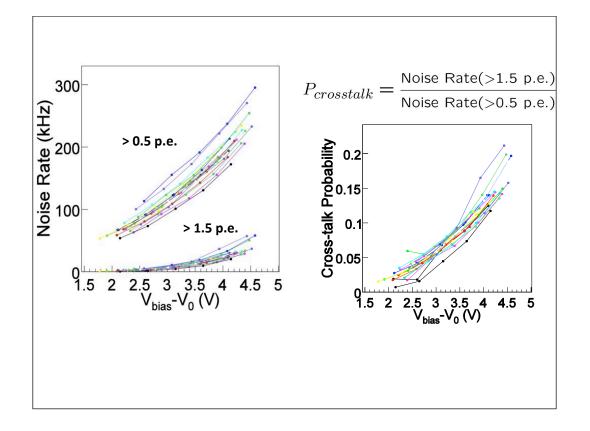
have rise time less then 1 nS (?).

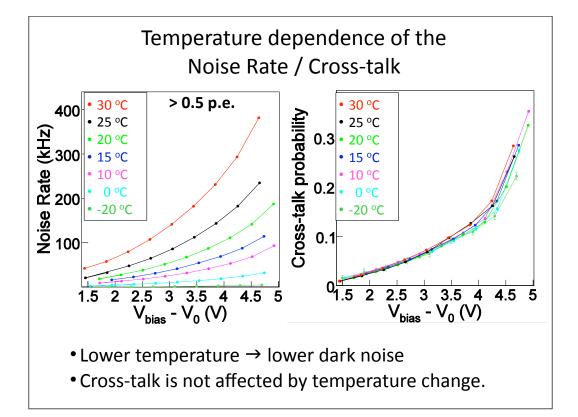


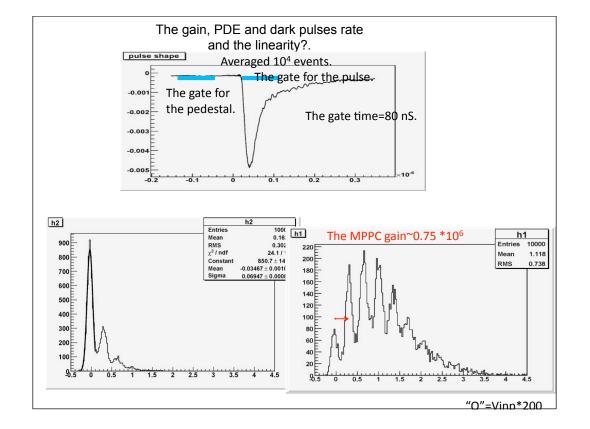
The LeCroy WaveRunner Xi-A

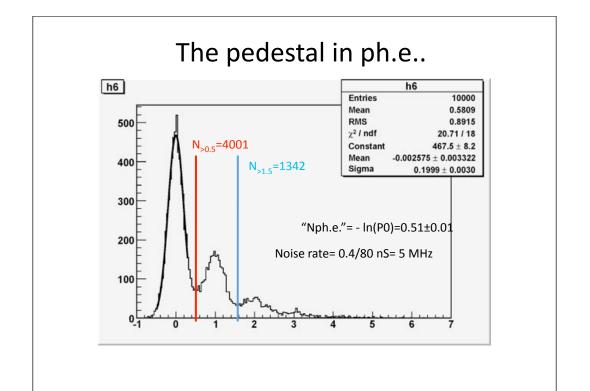




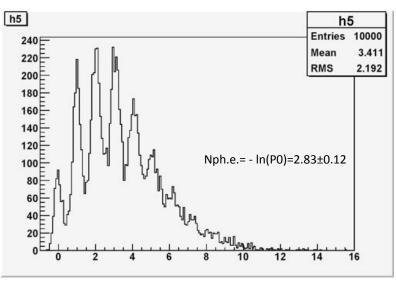


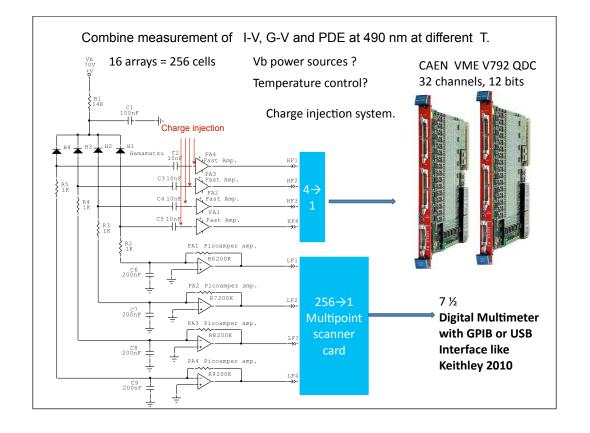












We are going to measure:

- The response of each cell of the array for LED pulses at different temperatures. We should measure a charge in the gate (gate time?) For gain determination we need measure photo electron peak position. We need to measure linearity region using a reference photo detector.
- The pedestal or noise measurement in the gate at the selected temperatures.
- The dark current measurements.
- All these measurements should be combined into one procedure, because the temperature stabilization is most important limiting factor.
- Temperature region is 0-25 °C: how many points ??? 2°C;5°C;10°C;15°C; 20°C;25°C.
- It mean that we need one day for one bunch of the arrays.
- To be in the schedule we have to test 16 arrays in parallel and make a set up for the test of $16 \times 16=256$ SiPM.

Table 1. Technical requirements for Silicon photomultiplier arrays for the Hall D BCAL. All requirements must be met at the nominal operating voltage and at a specified temperature in the range between 5 and 30° C.

There is a tradeoff between specific values of PDE and dark current to obtain a fixed detector resolution.

The tradeoff is made explicit in the following equation:

PDE > 0.0518 + \(\sqrt{0.002685} + 0.01629\delta DR(MHz)/100)\), where the dark rate DR is given in MHz;

Property	
Topolty	Specification
Gain at nominal operating voltage	(0.5–2)x10 ⁶
Photo-sensitive area	>140 mm²
Macroscopic active area coverage	> 75%
Number of micro-pixels	> 56000
Sensitivity to magnetic field	< 1% gain change at 3 T
PDE at 490 nm	> 19 % [Note 1]
Dark rate	< 100 MHz [Note 1]
Dark current	< 15 μA
Sensitivity to temperature	< 10% charge amplitude change/deg C
Output variation between tiles within one array	<10%
Variation of outputs between arrays	<10%
Nominal operating voltage	25-80 V
Nominal operating voltage above breakdown voltage	0.9–2.5 V
Fraction of multiple photoelectrons in dark noise	< 5% (preliminary)
Maximum package dimensions	< 16x21 mm² x 9 mm high
Package substrate	Al ₂ O ₃
Minimum area on back accessible for cooling	> 7.5 x 15 mm ²
Inputs	Positive bias voltage
Outputs	16 individual outputs
Output connector	Cu alloy pins on 0.05" centers
Rise time 10%–90%	< 15 ns
Pulse width 10%-10%	< 100 ns
Sensitivity to radiation	< 1%/Gy